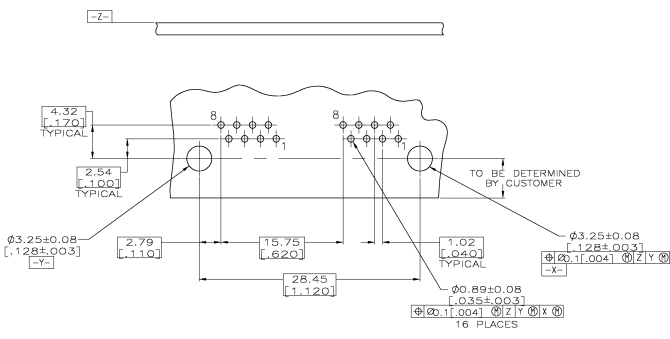
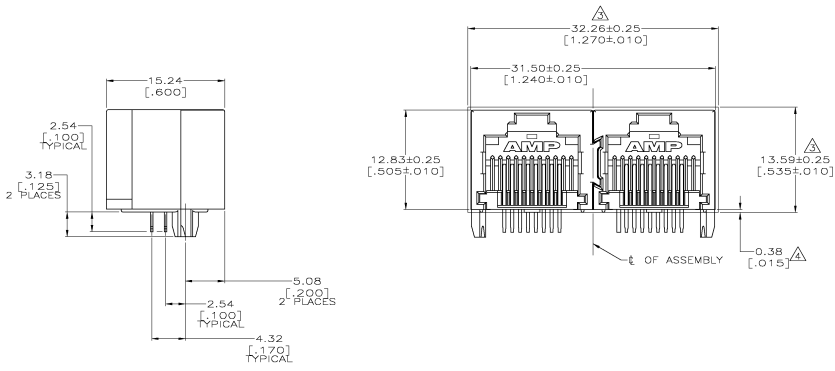


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 UNLESS INDICATED OTHERWISE  
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REV	DESCRIPTION	DATE	BY	CHK
AA 22				
A	EC0511-0201-04			

- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 µm [0.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.000050] MINIMUM THICK NICKEL.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	BY	APPROVED	REVISIONS	DATE	BY	CHK
DATE	BY	DATE	BY	APPROVED	REVISIONS	DATE	BY	CHK
108-1163-4		114-2154						

5406526-1 PART NUMBER

Yoko Electronics Corporation  
 Harrisburg, Pa 17105-3608

INVERTED MOD JACK ASSEMBLY, 1x2

108-1163-4

114-2154

DATE CODE

REV NO

00779

5406526

CUSTOMER DRAWING

REV A